

<b>Notice of References Cited</b>	Application/Control No. 09/452,367	Applicant(s)/Patent Under Reexamination SCHWEIKERT ET AL.	
	Examiner James M. Mitchell	Art Unit 2813	Page 1 of 1

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.